

# International IOR Rectifier

## HEXFET® POWER MOSFET

Provisional Data Sheet No. PD-9.425B

**JANTX2N6786**

**JANTXV2N6786**

**[REF:MIL-PRF-19500/556]**

**[GENERIC:IRFF310]**

**N-CHANNEL**

### 400 Volt, 3.6Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance. HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

### Product Summary

Part Number	BV <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
JANTX2N6786	400V	3.6Ω	1.25A
JANTXV2N6786			

### Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed


### Absolute Maximum Ratings

	Parameter	JANTX2N6786, JANTXV2N6786	Units
I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C	Continuous Drain Current	1.25	A
I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C	Continuous Drain Current	0.80	
I <sub>DM</sub>	Pulsed Drain Current ①	5.0	
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Max. Power Dissipation	15	W
	Linear Derating Factor	0.12	W/K ⑤
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V
dv/dt	Peak Diode Recovery dv/dt ③	4.0	V/ns
T <sub>J</sub>	Operating Junction	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range		
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10.5 seconds)	
	Weight	0.98 (typical)	

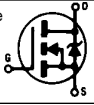


## JANTX2N6786, JANTXV2N6786 Device

### Electrical Characteristics @ $T_j = 25^\circ\text{C}$ (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	400	—	—	V	$V_{GS} = 0V, I_D = 1.0\text{ mA}$
$\Delta BVDSS/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.37	—	$V/^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D = 1.0\text{ mA}$
RDS(on)	Static Drain-to-Source On-State Resistance	—	—	3.6	$\Omega$	$V_{GS} = 10V, I_D = 0.80A$ ④
		—	—	4.15		$V_{GS} = 10V, I_D = 1.25A$
VGS(th)	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
gfs	Forward Transconductance	0.7	—	—	S (r)	$V_{DS} > 15V, I_{DS} = 0.80A$ ④
IDSS	Zero Gate Voltage Drain Current	—	—	25	$\mu\text{A}$	$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V$
		—	—	250		$V_{DS} = 0.8 \times \text{Max Rating}$ $V_{GS} = 0V, T_J = 125^\circ\text{C}$
IGSS	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20V$
IGSS	Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20V$
Qg	Total Gate Charge	6.7	—	8.4	nC	$V_{GS} = 10V, I_D = 1.25A$
Qgs	Gate-to-Source Charge	0.2	—	1.5		$V_{DS} = \text{Max. Rating} \times 0.5$ see figures 6 and 13
Qgd	Gate-to-Drain ("Miller") Charge	3.5	—	5.0		
td(on)	Turn-On Delay Time	—	—	15	ns	$V_{DD} = 200V, I_D = 1.25A,$ $R_G = 7.5\Omega, V_{GS} = 10V$
tr	Rise Time	—	—	20		
td(off)	Turn-Off Delay Time	—	—	35		
tf	Fall Time	—	—	30		
LD	Internal Drain Inductance	—	5.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die. Modified MOSFET symbol showing the internal inductances. 
LS	Internal Source Inductance	—	15	—		
Cjss	Input Capacitance	—	170	—	pF	$V_{GS} = 0V, V_{DS} = 25V$ $f = 1.0\text{ MHz}$ see figure 5
Coss	Output Capacitance	—	49	—		
Crss	Reverse Transfer Capacitance	—	10	—		

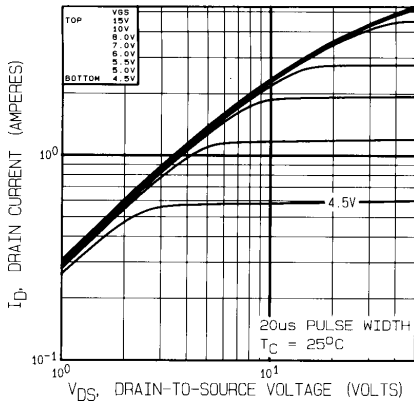
### Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current (Body Diode)	—	—	1.25	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier. 
ISM	Pulse Source Current (Body Diode) ①	—	—	5.0		
VSD	Diode Forward Voltage	—	—	1.4	V	$T_j = 25^\circ\text{C}, I_S = 1.25A, V_{GS} = 0V$ ④
trr	Reverse Recovery Time	—	—	540	ns	$T_j = 25^\circ\text{C}, I_F = 1.25A, di/dt \leq 100A/\mu\text{s}$ $V_{DD} \leq 50V$ ④
QRR	Reverse Recovery Charge	—	—	4.5	$\mu\text{C}$	
ton	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by $L_S + L_D$ .				

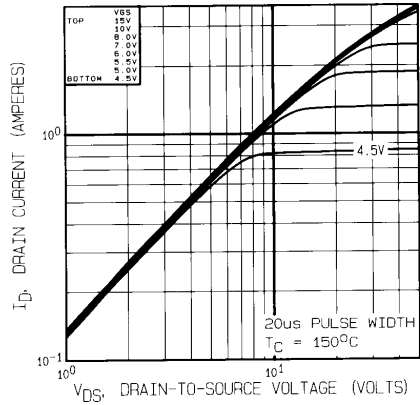
### Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RthJC	Junction-to-Case	—	—	8.3	K/W	Typical socket mount
RthJA	Junction-to-Ambient	—	—	175		

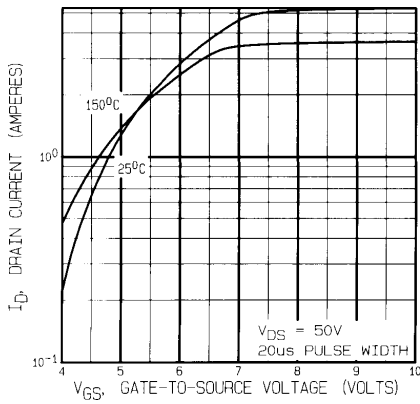
# JANTX2N6786, JANTXV2N6786 Device



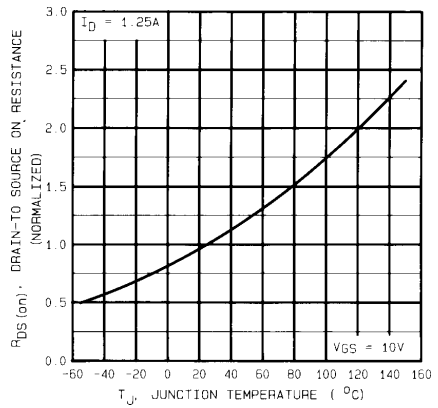
**Fig. 1 — Typical Output Characteristics**  
 $T_c = 25^\circ\text{C}$



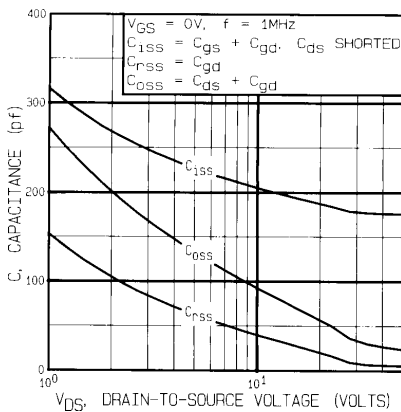
**Fig. 2 — Typical Output Characteristics**  
 $T_c = 150^\circ\text{C}$



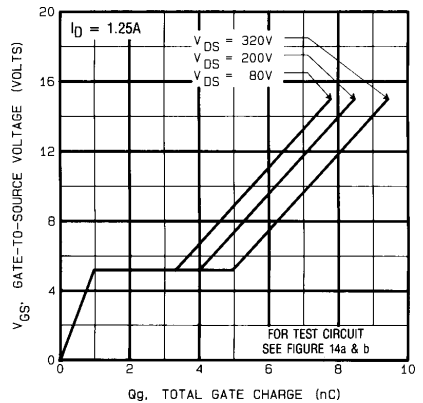
**Fig. 3 — Typical Transfer Characteristics**



**Fig. 4 — Normalized On-Resistance Vs. Temperature**

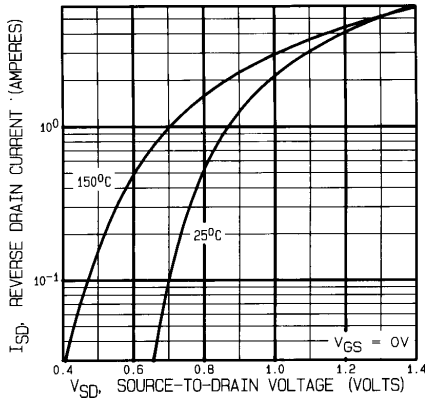


**Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage**

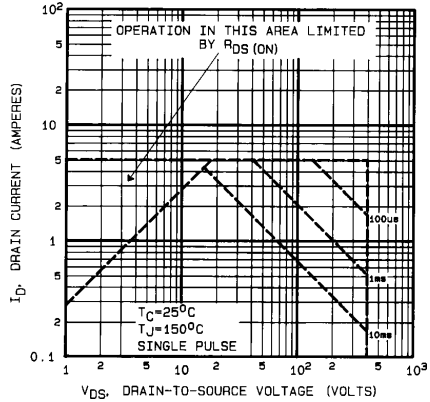


**Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage**

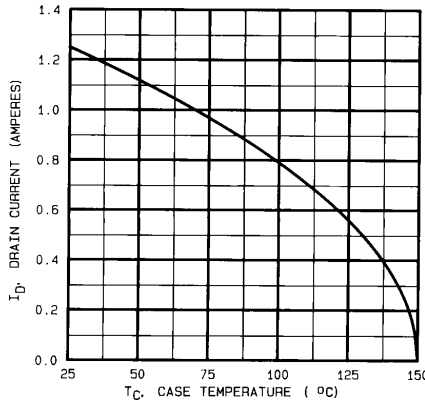
# JANTX2N6786, JANTXV2N6786 Device



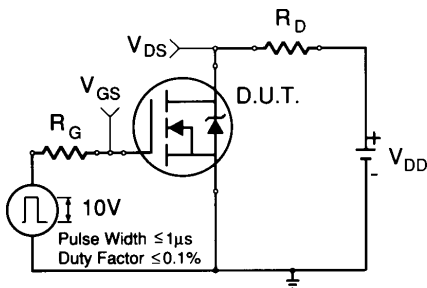
**Fig. 7 — Typical Source-to-Drain Diode Forward Voltage**



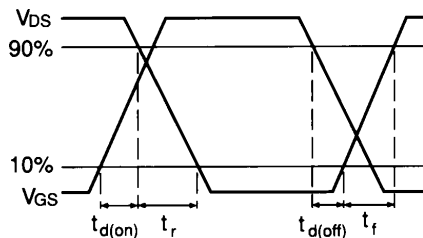
**Fig. 8 — Maximum Safe Operating Area**



**Fig. 9 — Maximum Drain Current Vs. Case Temperature**



**Fig. 10a — Switching Time Test Circuit**



**Fig. 10b — Switching Time Waveforms**

# JANTX2N6786, JANTXV2N6786 Device

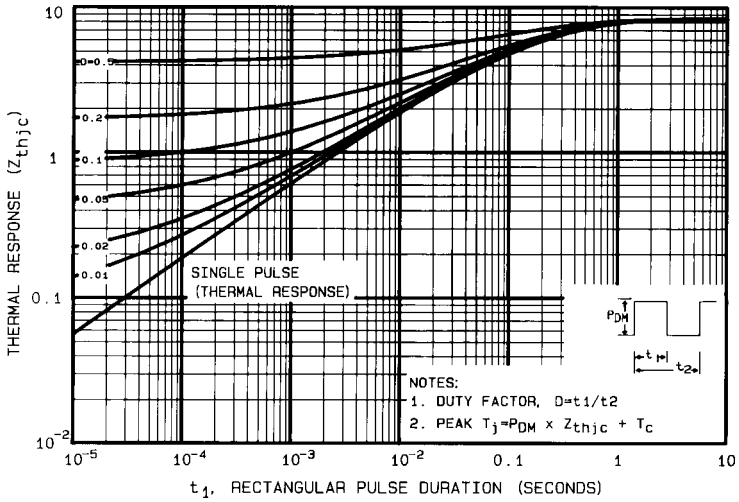


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

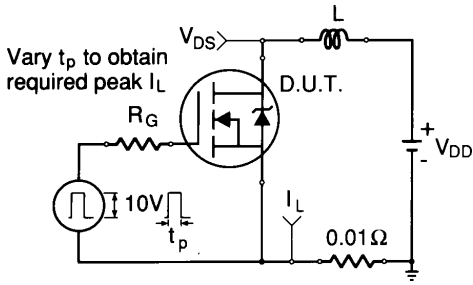


Fig. 12a — Unclamped Inductive Test Circuit

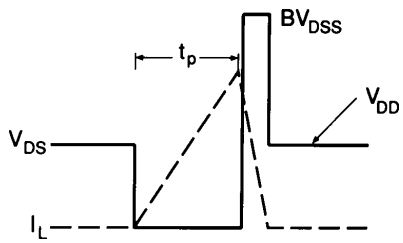


Fig. 12b — Unclamped Inductive Waveforms

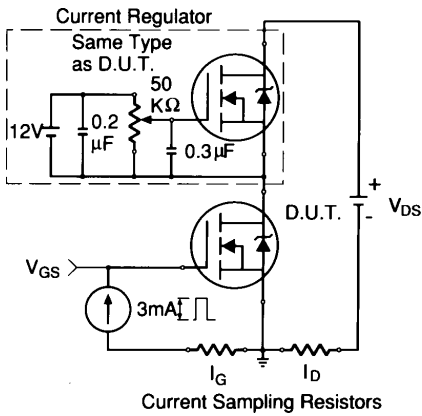


Fig. 13a — Gate Charge Test Circuit

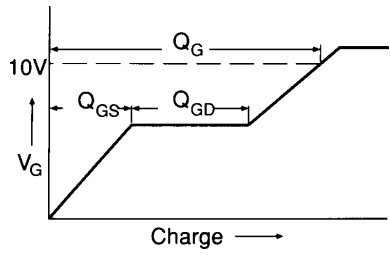
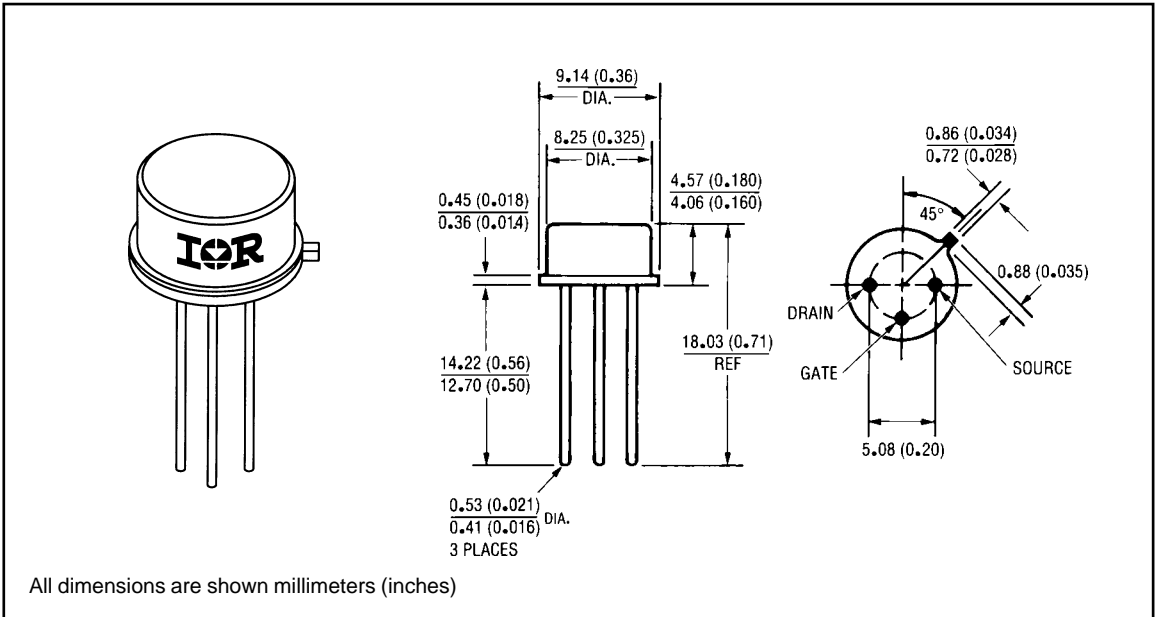


Fig. 13b — Basic Gate Charge Waveform

## JANTX2N6786, JANTXV2N6786 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature. (see figure 11)
- ② @  $V_{DD} = 50V$ , Starting  $T_J = 25^\circ C$ ,  
 $EAS = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]$   
 Peak  $I_L = 1.25A$ ,  $V_{GS} = 10V$ ,  $25 \leq R_G \leq 200\Omega$
- ③  $ISD \leq 1.25A$ ,  $di/dt \leq 40A/\mu s$ ,  
 $V_{DD} \leq BV_{DSS}$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤  $K/W = ^\circ C/W$   
 $W/K = W/^\circ C$

### Case Outline and Dimensions — TO-205AF (Modified TO-39)



International  
**IOR** Rectifier

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Data and specifications subject to change without notice 10/96